# Dual N-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY | | | |
|---|---|---|---|
| $V_{DS}$ (V) | $R_{DS(on)}$ (Ω) | $I_D$ (A) | $Q_g$ (Typ.) |
| 30 | 0.009 at $V_{GS}$ = 10 V | 45 | 8.1 nC |
| | 0.012at $V_{GS}$ = 4.5 V | 32 | |

## FEATURES

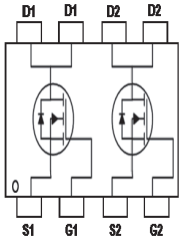
- DT-Trench Power MOSFET
- 100 % UIS Tested
- 100 % $R_g$ Tested

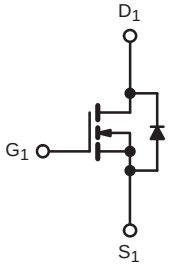
RoHS COMPLIANT

## APPLICATIONS

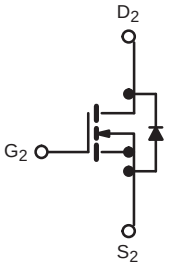
- Synchronous buck
- DC/DC conversion
- Half bridge
- POL

PDFN3.3X 3.3


N-Channel MOSFET




N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS ($T_A$ = 25 °C, unless otherwise noted) | | | | |
|---|---|---|---|---|
| PARAMETER | | SYMBOL | LIMIT | UNIT |
| Drain-source voltage | | $V_{DS}$ | 30 | V |
| Gate-source voltage | | $V_{GS}$ | +20 | |
| Continuous drain current ($T_J$ = 150 °C) | $T_C$ = 25 °C | $I_D$ | 45 | A |
| | $T_C$ = 70 °C | | 26.7 | |
| | $T_A$ = 25 °C | | 15.7 [b, c] | |
| | $T_A$ = 70 °C | | 12.5 [b, c] | |
| Pulsed drain current (t = 100 µs) | | $I_{DM}$ | 180 | |
| Continuous source current (MOSFET diode conduction) | $T_C$ = 25 °C | $I_S$ | 45 | |
| | $T_A$ = 25 °C | | 3.9 [b, c] | |
| Single pulse avalanche current | L = 0.1 mH | $I_{AS}$ | 10 | |
| Single pulse avalanche energy | | $E_{AS}$ | 19 | mJ |
| Maximum power dissipation | $T_C$ = 25 °C | $P_D$ | 22 | W |
| | $T_C$ = 70 °C | | 12.7 | |
| | $T_A$ = 25 °C | | 6.7 [b, c] | |
| | $T_A$ = 70 °C | | 4.1 [b, c] | |
| Operating junction and storage temperature range | | $T_J$, $T_{stg}$ | -55 to +150 | °C |
| Soldering recommendations (peak temperature) | | | 260 | |

**Notes**

a. $T_C$ = 25 °C

b. Surface mounted on 1" x 1" FR4 board

c. t = 10 s

| THERMAL RESISTANCE RATINGS | | SYMBOL | TYPICAL | MAXIMUM | UNIT |
|---|---|---|---|---|---|
| Maximum junction-to-ambient [a, b] | t ≤ 10 s | $R_{thJA}$ | 27 | 34 | °C/W |
| Maximum junction-to-case (drain) | Steady state | $R_{thJC}$ | 6 | 7.5 | |

**Notes**

a. Surface mounted on 1" x 1" FR4 board

b. Maximum under steady state conditions is 69 °C/W

| **SPECIFICATIONS** ($T_J$ = 25 °C, unless otherwise noted) | | | | | | |
|---|---|---|---|---|---|---|
| **PARAMETER** | **CHANNEL-1 AND CHANNEL-2** | | | | | |
| | **SYMBOL** | **TEST CONDITIONS** | **MIN.** | **TYP.** | **MAX.** | **UNIT** |
| **Static** | | | | | | |
| Drain-source breakdown voltage | $V_{DS}$ | $V_{GS}$ = 0 V, $I_D$ = 250 µA | 30 | - | - | V |
| Gate-source threshold voltage | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$, $I_D$ = 250 µA | 1 | - | 2.4 | |
| Gate-source leakage | $I_{GSS}$ | $V_{DS}$ = 0 V, $V_{GS}$ = +20 V / -16 V | - | - | ± 100 | nA |
| Zero gate voltage drain current | $I_{DSS}$ | $V_{DS}$ = 24 V, $V_{GS}$ = 0 V | - | - | 1 | µA |
| | | $V_{DS}$ = 24 V, $V_{GS}$ = 0 V, $T_J$ = 55 °C | - | - | 5 | |
| On-state drain current [a] | $I_{D(on)}$ | $V_{DS}$ ≥ 5 V, $V_{GS}$ = 10 V | 45 | - | - | A |
| Drain-source on-state resistance [a] | $R_{DS(on)}$ | $V_{GS}$ = 10 V, $I_D$ = 10 A | - | 0.0090 | 0.012 | Ω |
| | | $V_{GS}$ = 4.5 V, $I_D$ = 7 A | - | 0.0120 | 0.018 | |
| Forward transconductance [a] | $g_{fs}$ | $V_{DS}$ = 10 V, $I_D$ = 10 A | - | 57 | - | S |
| **Dynamic [b]** | | | | | | |
| Input capacitance | $C_{iss}$ | $V_{DS}$ = 15 V, $V_{GS}$ = 0 V, f = 1 MHz | - | 880 | - | pF |
| Output capacitance | $C_{oss}$ | | - | 250 | - | |
| Reverse transfer capacitance | $C_{rss}$ | | - | 30 | - | |
| $C_{rss}/C_{iss}$ ratio | | | - | 0.052 | 0.103 | |
| Total gate charge | $Q_g$ | $V_{DS}$ = 15 V, $V_{GS}$ = 10 V, $I_D$ = 10 A | - | 8.1 | 12.2 | nC |
| | | $V_{DS}$ = 15 V, $V_{GS}$ = 4.5 V, $I_D$ = 7 A | - | 3.7 | 4.5 | |
| Gate-source charge | $Q_{gs}$ | | - | 2.4 | - | |
| Gate-drain charge | $Q_{gd}$ | | - | 0.67 | - | |
| Gate resistance | $R_g$ | f = 1 MHz | 0.24 | 1.2 | 2.4 | Ω |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}$ = 15 V, $R_L$ = 1.2 Ω, $I_D$ ≅ 10 A, $V_{GEN}$ = 10 V, $R_g$ = 1 Ω | - | 10 | 20 | ns |
| Rise time | $t_r$ | | - | 6 | 12 | |
| Turn-off delay time | $t_{d(off)}$ | | - | 18 | 36 | |
| Fall time | $t_f$ | | - | 8 | 16 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}$ = 15 V, $R_L$ = 1.2 Ω, $I_D$ ≅ 7 A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 Ω | - | 15 | 30 | |
| Rise time | $t_r$ | | - | 180 | 360 | |
| Turn-off delay time | $t_{d(off)}$ | | - | 20 | 40 | |
| Fall time | $t_f$ | | - | 15 | 30 | |

| **SPECIFICATIONS** ($T_J$ = 25 °C, unless otherwise noted) | | | | | | |
|---|---|---|---|---|---|---|
| **PARAMETER** | **SYMBOL** | **TEST CONDITIONS** | **MIN.** | **TYP.** | **MAX.** | **UNIT** |
| **Drain-source Body Diode Characteristics** | | | | | | |
| Continuous source-drain diode current | $I_S$ | $T_C$ = 25°C | - | - | 45 | A |
| Pulse diode forward current | $I_{SM}$ | | - | - | 180 | |
| Body diode voltage | $V_{SD}$ | $I_S$ = 12.5 A, $V_{GS}$ = 0 V | - | 0.7 | 1.2 | V |
| Body diode reverse recovery time | $t_{rr}$ | $I_F$ = 12.5 A, di/dt = 100 A/µs, $T_J$ = 25 °C | - | 15 | 30 | ns |
| Body diode reverse recovery charge | $Q_{rr}$ | | - | 4.3 | 8.6 | nC |
| Reverse recovery fall time | $t_a$ | | - | 8 | - | ns |
| Reverse recovery rise time | $t_b$ | | - | 7 | - | |

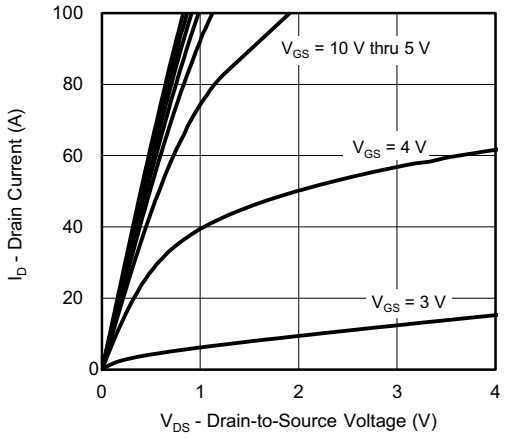
**Notes**

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %

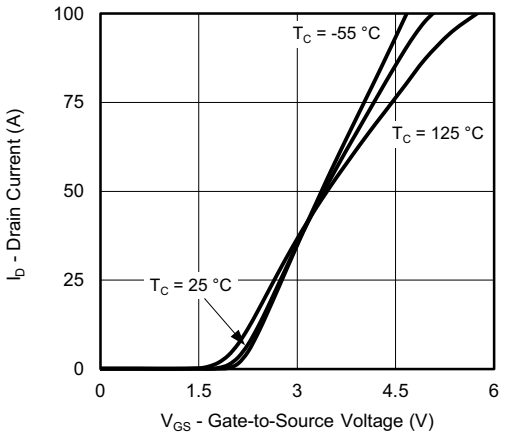
b. Guaranteed by design, not subject to production testing

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

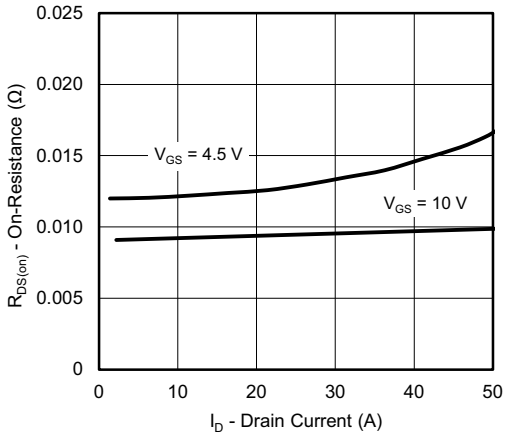
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



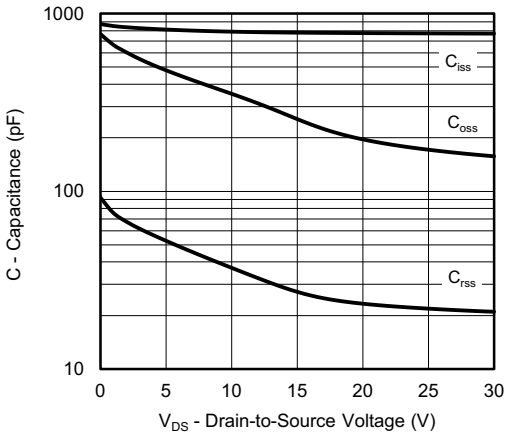

**Output Characteristics**



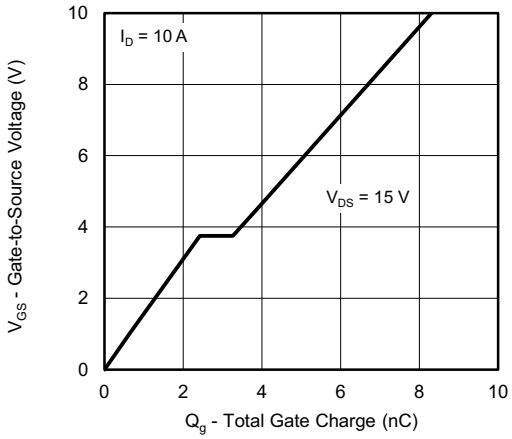

**Transfer Characteristics**



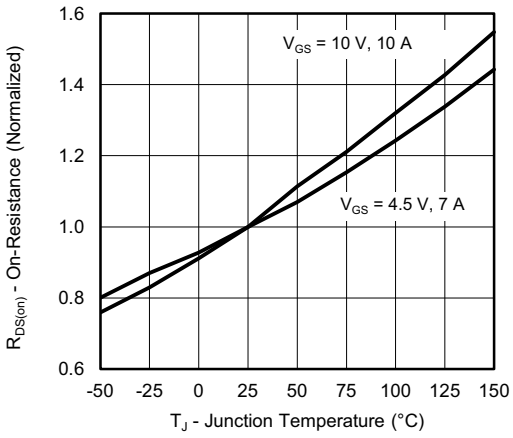

**On-Resistance vs. Drain Current and Gate**




**Capacitance**

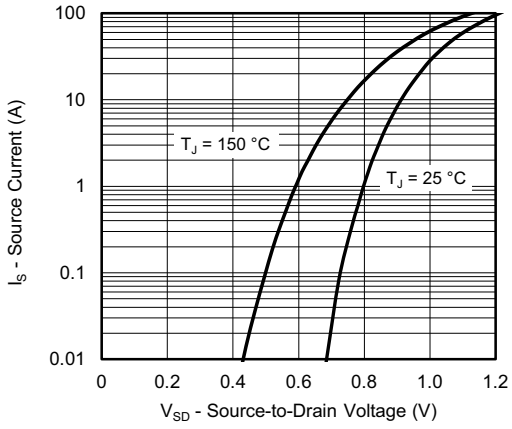



**Gate Charge**

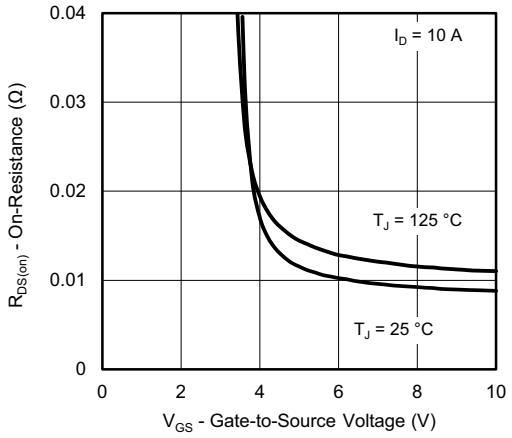



**On-Resistance vs. Junction Temperature**

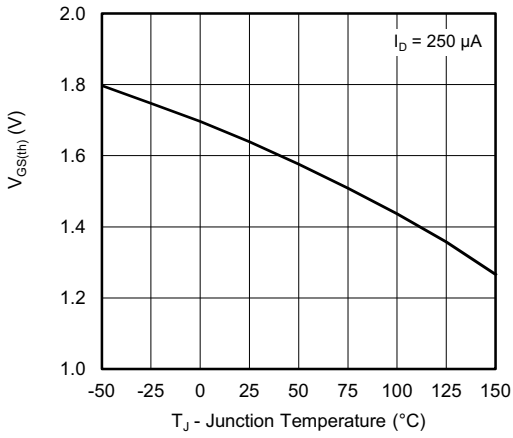
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



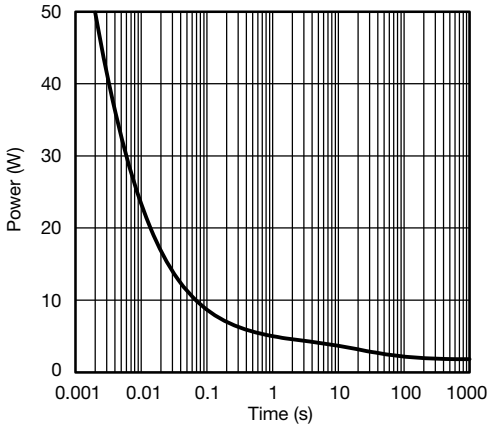

**Source-Drain Diode Forward Voltage**




**On-Resistance vs. Gate-to-Source Voltage**

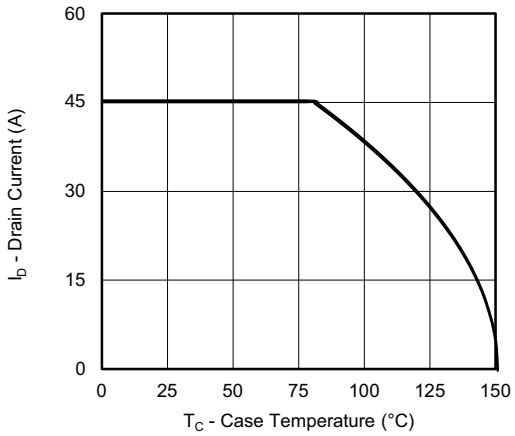



**Threshold Voltage**

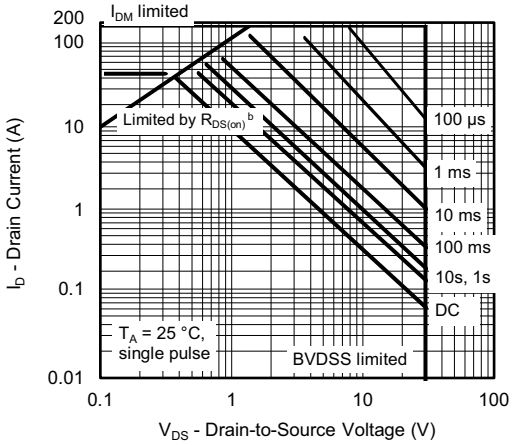



**Single Pulse Power**

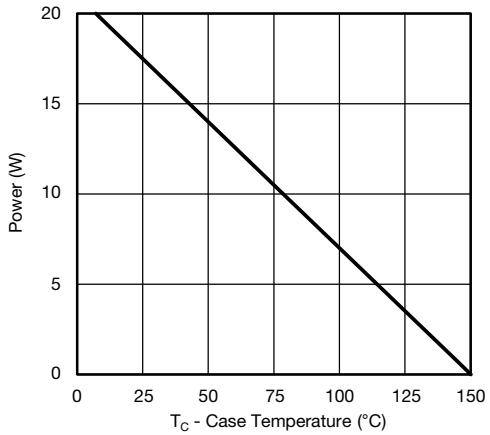
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



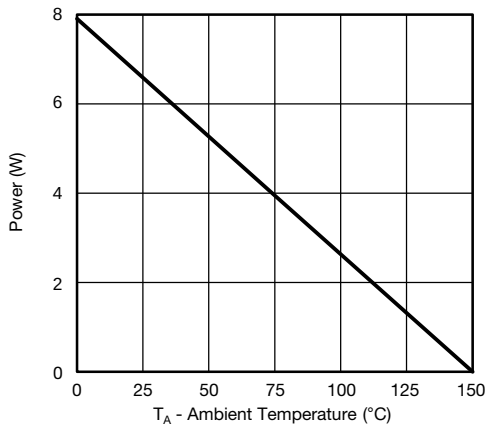

**Current Derating [a]**




**Safe Operating Area, Junction-to-Ambient**




**Power, Junction-to-Case**



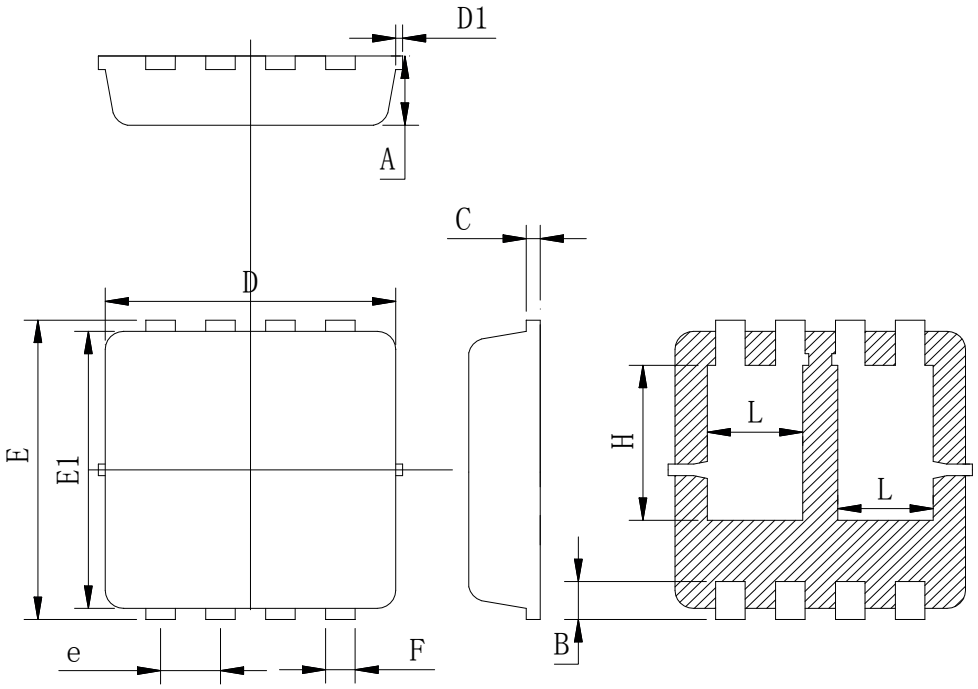

**Power, Junction-to-Ambient**

**Notes**

a. The power dissipation $P_D$ is based on $T_J$ max. = 150 °C, using junction-to-ambient thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

b. $V_{GS}$ > minimum $V_{GS}$ at which $R_{DS(on)}$ is specified

# PDFN 3.3X3.3-D PACKAGE OUTLINE




COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

| Symbol | Min | Typ | Max |
|---|---|---|---|
| A | 0.680 | 0.775 | 0.920 |
| B | 0.25 | 0.38 | 0.55 |
| C | 0.08 | 0.15 | 0.25 |
| D | 2.95 | 3.10 | 3.25 |
| D1 | | | 0.12 |
| E | 3.20 | 3.30 | 3.40 |
| E1 | 2.85 | 3.00 | 3.15 |
| e | 0.50 | 0.65 | 0.80 |
| F | 0.23 | 0.32 | 0.41 |
| H | 1.53 | 1.73 | 1.93 |
| L | 0.83 | 1.03 | 1.23 |

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